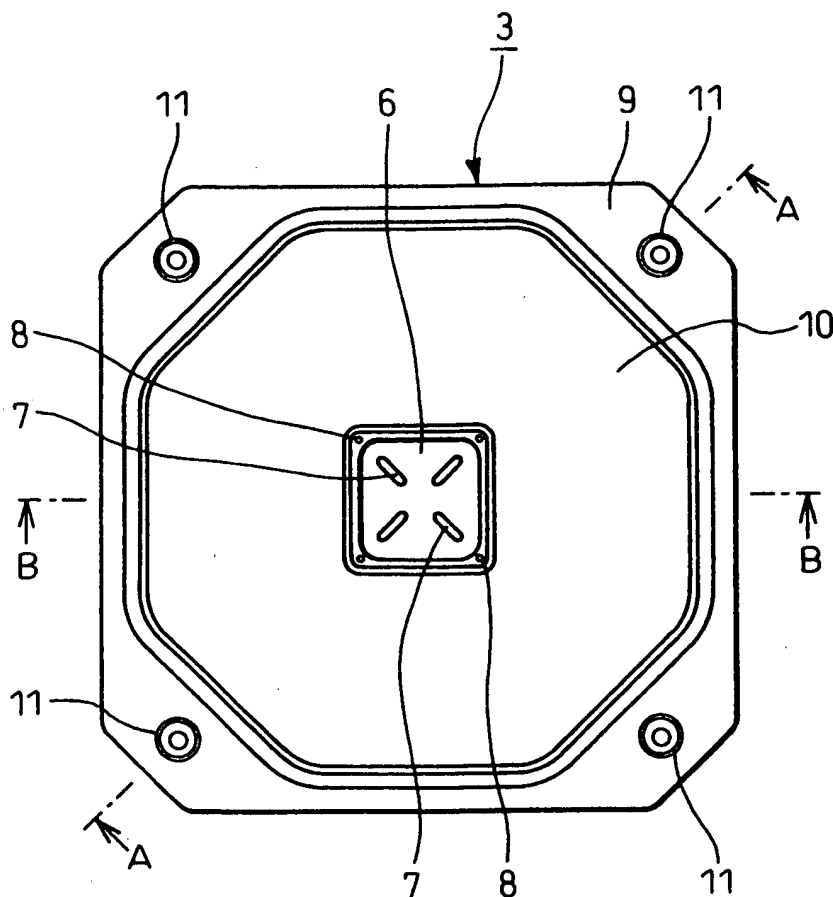


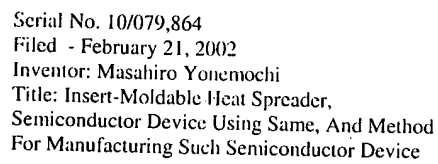


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Fig.1



This diagram shows a cross-section of a substrate 4 with a conductive layer 9. A conductive paste 10 is applied to the conductive layer 9, and a conductive paste 11 is applied to the substrate 4. The conductive paste 10 is shown as a layer with a wavy, irregular top surface, while the conductive paste 11 is shown as a layer with a smooth, flat top surface.



A cross-sectional view of a substrate 4. A conductive layer 9 is formed on the top surface of the substrate 4. A conductive paste 10 is applied to the top surface of the conductive layer 9. The conductive paste 10 is shown with a hatched pattern. A conductive paste 11 is applied to the bottom surface of the substrate 4. The conductive paste 11 is shown with a dotted pattern. A conductive paste 3 is applied to the top surface of the substrate 4, between the conductive layer 9 and the conductive paste 10. The conductive paste 3 is shown with a hatched pattern.



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Fig.4(a)

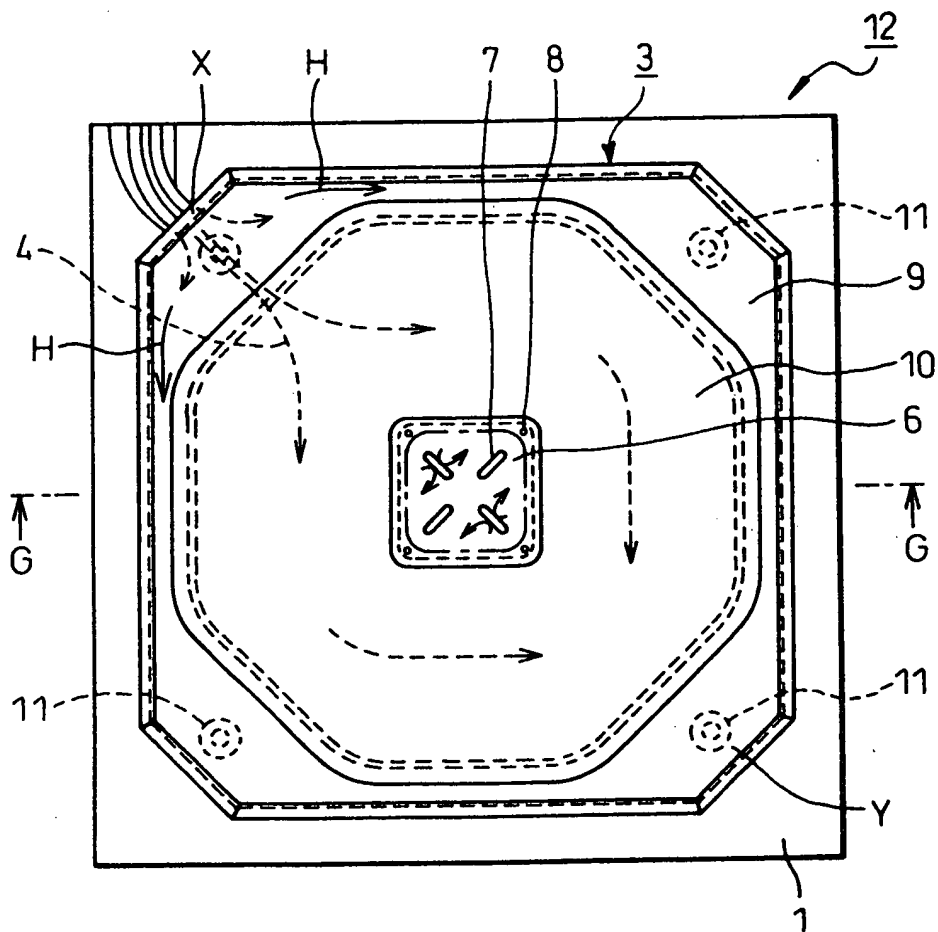
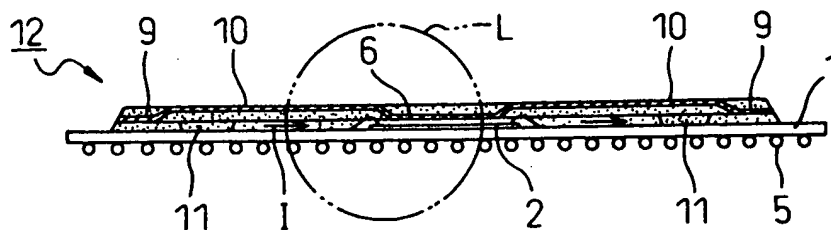


Fig.4(b)





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Fig.4(c)

